## SV2081A

Front Access 2U 4-node Server to Address Growing Computing Needs



## High-reliable Network Connectivity

The standard-compliant OCP 3.0 slot enables installation of a NIC to provide high bandwidth and ultra-low latency for server networking, and features tool-less design for easy serviceability.

## Application

Hyperscale Data Center

High Performance Computing

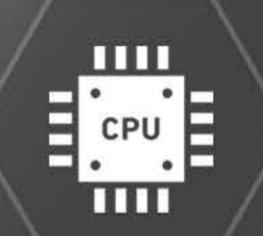
Composable Disaggregated Infrastructure

## High-density Computing in a Compact Design

Equipped with four independent nodes, the server delivers unprecedented performance to handle complex workloads in a small chassis, making it a great choice to increase compute density in limited spaces.

## Highly Convenient Front Access Design

The four nodes are front accessible, which is convenient for users to access the node from the front, and to eliminate the need of maintenance behind the rack where space is minimal.



8 x 3<sup>rd</sup> Generation AMD EPYC<sup>TM</sup> Processors



64 x DDR4 RDIMM/ LRDIMM



Front Access Design



1+1 Redundancy, Platinum Level



2U Rackmount

## High-speed PCIe Expansion Capability

Supporting PCIe Gen4, the product offers a superior bandwidth of 16 GT/s, double the speed of PCIe Gen3, to enable faster data transfer rate for versatile I/O options.





# SV2081A

## Specifications



North America: +1 408-727-8060

2 x PCle Gen4 x16 LP slots per Node

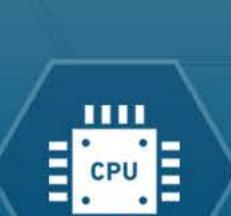
1 x OCP 3.0 NIC PCIe Gen4 x16 per Node



Email: Sales@ingrasys.com

**Expansion Slots** 





#### Processor

Two 2<sup>nd</sup>/3<sup>rd</sup> Generation AMD EPYC<sup>TM</sup> Processors, up to 24 Cores, 240W (TDP) per Node



#### Management

1 x ASPEED AST2500 BMC per Node Support Intelligent Platform Management Interface v.2.0



#### Memory

16 x DDR4 3200MHz RDIMM/LRDIMM per Node, 1 x NVDIMM per Node



#### **PSUs**

1+1 Redundant 3000W Platinum Power Supplies



#### Fans

3 x 40\*56mm per Node, 12 x per Chassis



### Storage

1 x SATA/NVMe M.2 (2280/22110) per Node 1 x SATA M.2 (2280/22110) per Node



### Front Panel (per Node)

1 x Power Button with LED

1 x UID LED

1 x System Health LED

1 x RJ45 for BMC Dedicated Management

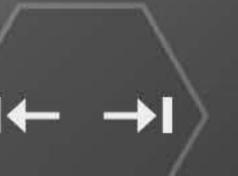
1 x VGA

2 x USB 3.0



## TPM

1 x TPM 2.0 Module per Node



#### Chassis Dimensions $(H \times W \times D)$

3.42" x 17.6" x 26.76" / 87.0mm x 447.0mm x 679.8mm

Operating Temperature 5°C to 35°C (41°F to 95°F)



## Non-operating Temperature -40°C to 70°C (-40°F to 158°F)

Operating Relative Humidity 8% to 90%RH

Non-operating Relative Humidity



#### Certification

FCC/CE/UL/CB/BSMI



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5% to 90%RH